

General Description:

Using owner proprietary trench design, advanced Field Stop (FS) technology and integrated with Free Wheeling Diode, offering superior conduction and switching performances.

V_{CES}	1350	V
I_C	30	A
P_{tot} ($T_C=25^{\circ}C$)	278	W
$V_{CE(sat)}$	1.6	V

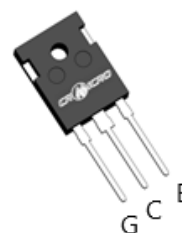
Features:

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage: $V_{CE(sat)}$ TYP=1.6V @ $I_C=30A, V_{GE}=15V$

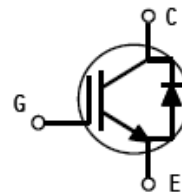
Applications

- Power switch circuit of induction cooker (IH).

Outline : TO-247



Inner Circuit:



Package Parameters

Type	Marking	Package	Packing
CRG30T135AKR5H	G30T135AKR5H	TO-247	Tube

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified):

Symbol	Parameter	Rating	Unit
V_{CES}	Collector-Emitter Voltage	1350	V
V_{GES}	Gate- Emitter Voltage	± 20	V
V_{GES}	Gate- Emitter Voltage ($t_p \leq 10\mu\text{s}, D < 0.01$)	± 30	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	60	A
	Collector Current @ $T_C = 100^\circ\text{C}$	30	
I_{CM}^{a1}	Pulsed Collector Current	120	A
I_F	Diode Continuous Forward Current @ $T_C = 25^\circ\text{C}$	60	A
	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	30	
I_{FM}	Diode Maximum Forward Current	120	A
P_D	Power Dissipation @ $T_C = 25^\circ\text{C}$	278	W
	Power Dissipation @ $T_C = 100^\circ\text{C}$	139	
T_{vjop}^{a2}	Operating Junction temperature range	$-40 \sim 175$	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	$-55 \sim 150$	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	270	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R\theta_{JC}$	Thermal Resistance, Junction to case for IGBT	--	0.54	$^\circ\text{C}/\text{W}$
$R\theta_{JA}$	Thermal Resistance, Junction to Ambient	--	40	$^\circ\text{C}/\text{W}$

Electrical Characteristics of the IGBT ($T_C = 25^\circ\text{C}$ unless otherwise specified):

Symbol	Parameter	Conditions	Value			Unit
			Min.	Typ	Max.	
OFF Characteristics						
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	V _{GE} =0V,I _{CE} =250uA	1350	--	--	V
I _{CES}	Collector Cut-off Current	V _{GE} =0V,V _{CE} =1350V	--	--	1.0	mA
I _{GES(F)}	Gate-Emitter Forward Leakage Current	V _{GE} =+20V	--	--	+250	nA
I _{GES(R)}	Gate-Emitter Reverse Leakage Current	V _{GE} =-20V	--	--	-250	nA
ON Characteristics						
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =30A ,V _{GE} =15V @ T _C = 25 °C	--	1.6	2.4	V
		I _C =30A ,V _{GE} =15V @ T _C =175 °C	--	2.0	--	V
V _{GE(th)}	Gate - Emitter Threshold Voltage	I _C =250uA ,V _{CE} =V _{GE}	4.5	5.7	7.0	V

Pulse width $t_p \leq 300\mu s, \delta \leq 2\%$						
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE}=30V, V_{GE}=0V$ $f=1MHz$	--	4025	--	pF
C_{oes}	Output Capacitance		--	53	--	
C_{res}	Reverse Transfer Capacitance		--	20	--	
$t_{d(off)}$	Turn-Off Delay Time	$V_{CE}=600V, I_C=30A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_J=25^\circ C$	--	192	--	ns
t_f	Fall Time		--	136	--	
E_{off}	Turn-Off Switching Loss		--	1.28	--	mJ
$t_{d(off)}$	Turn-Off Delay Time	$V_{CE}=600V, I_C=30A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_J=175^\circ C$	--	244	--	ns
t_f	Fall Time		--	247	--	
E_{off}	Turn-Off Switching Loss		--	2.02	--	mJ
Q_g	Total Gate Charge	$V_{CE}=1080V, I_C=30A,$ $V_{GE}=15V$	--	213	--	nC
Q_{ge}	Gate to Emitter Charge		--	29	--	
Q_{gc}	Gate to Collector Charge		--	91	--	
V_F	Diode Forward Voltage	$I_F=30A \quad TC=25^\circ C$	--	1.7	2.6	V
		$I_F=30A \quad TC=175^\circ C$	--	1.95	--	V

Notes:

a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: Overload condition, it is allowed to operate under the maximum junction temperature $T_{vjop} = 175^\circ C$, the maximum duty cycle is less than 20% (lasting for 60s at most)

Typical Performance Characteristics

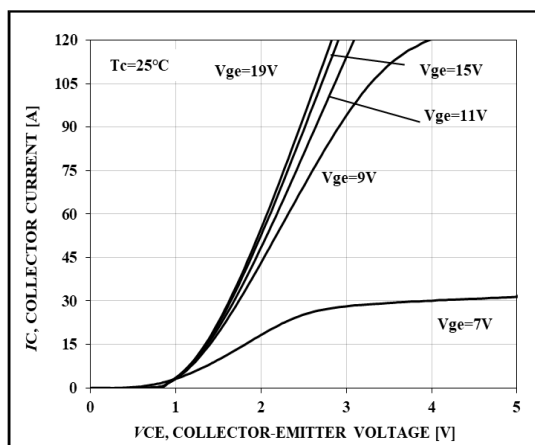


Figure 1. Output Characteristics

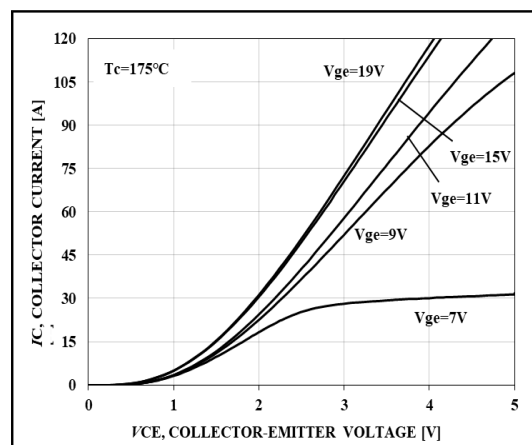


Figure 2. Output Characteristics

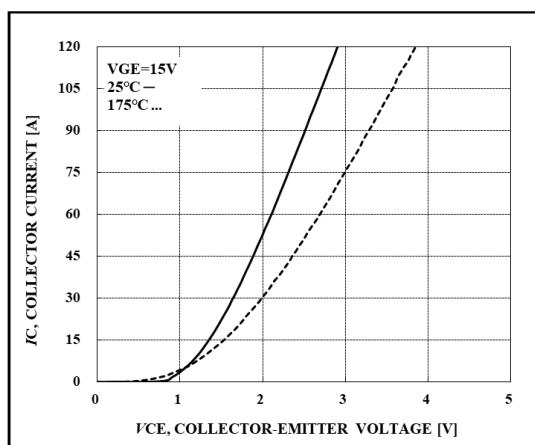


Figure 3. Saturation Voltage Characteristics

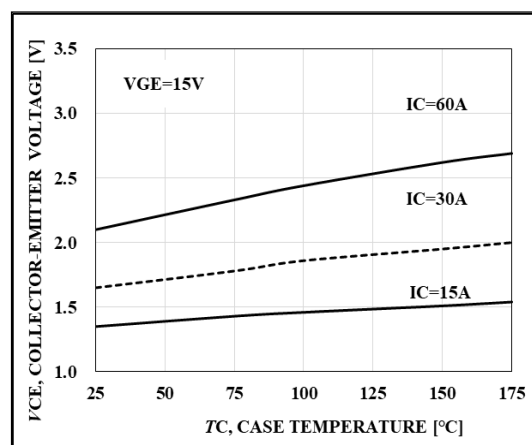


Figure 4. Saturation Voltage - T_C Characteristics

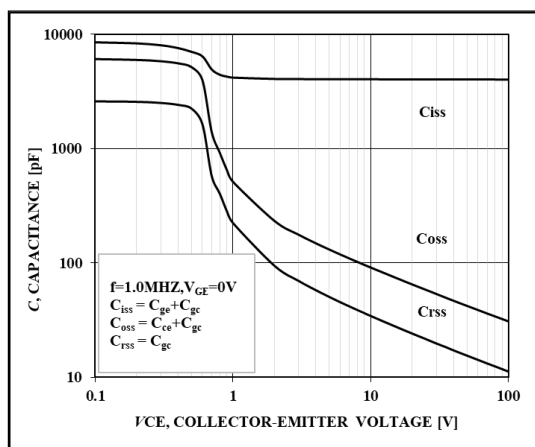


Figure 5. Capacitance Characteristics

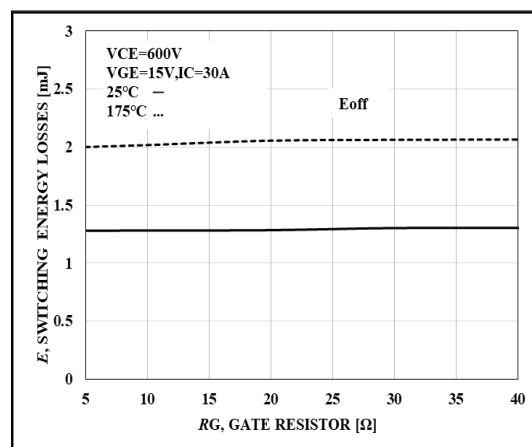


Figure 6. Switching Loss- R_G Characteristics

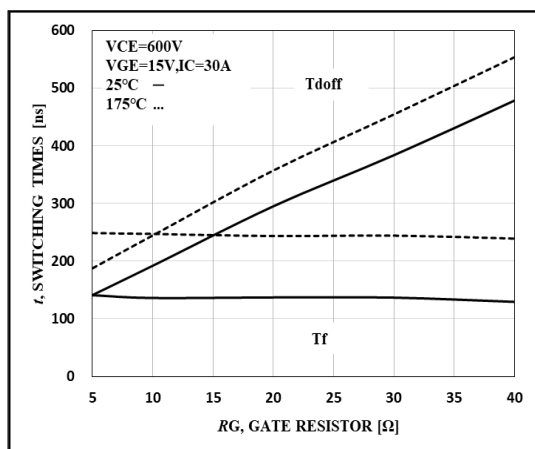


Figure 7. Switching Time- R_G Characteristics

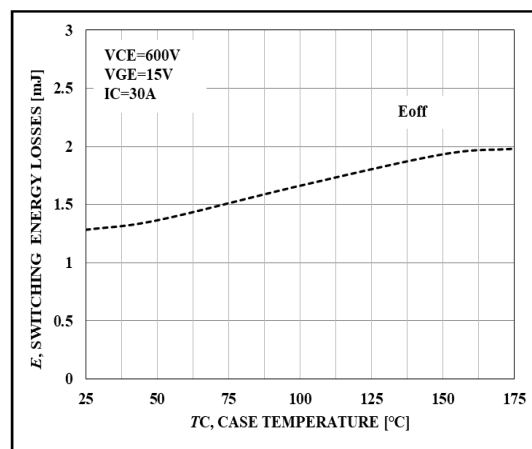


Figure 8. Switching Loss- T_C Characteristics

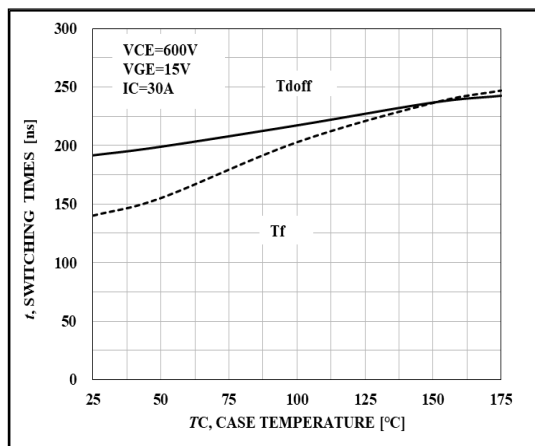


Figure 9. Switching Time- T_C Characteristics

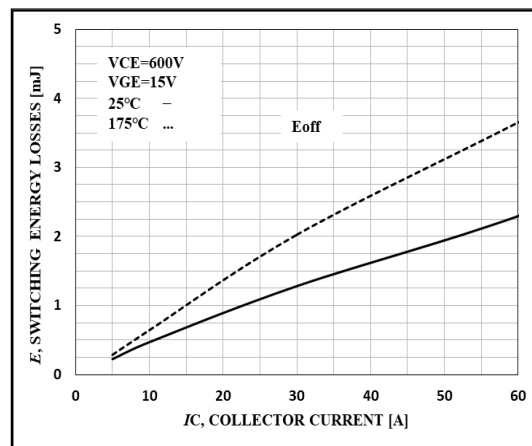


Figure 10. Switching Loss- I_C Characteristics

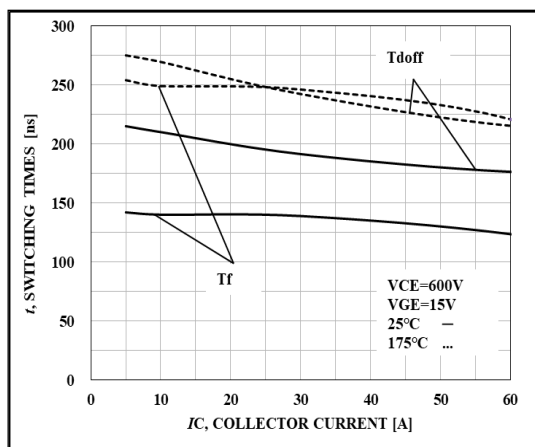


Figure 11. Switching Time- I_C Characteristics

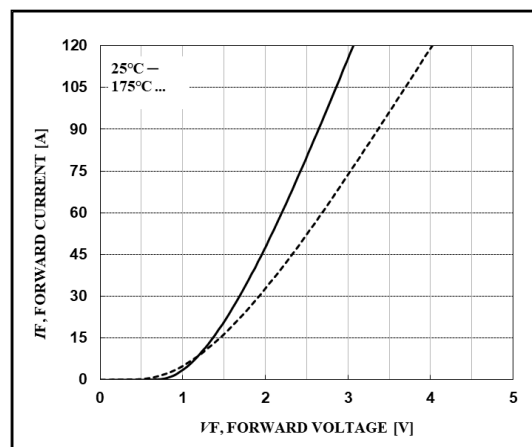


Figure 12. Diode Forward Characteristics

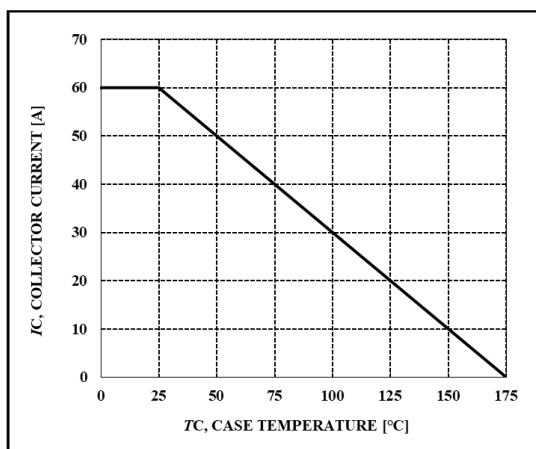


Figure 13. Collector Current-Tc Characteristics
(Tj ≤ 175°C)

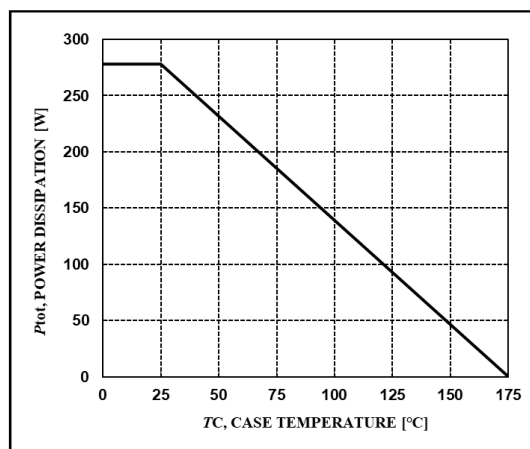


Figure 14. Power Dissipation-Tc Characteristics
(Tj ≤ 175°C)

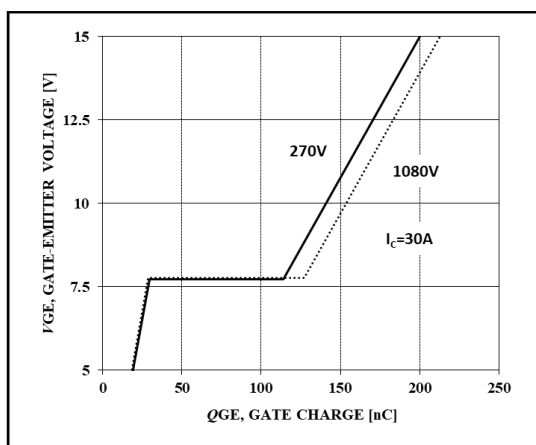


Figure 15. Gate Charge Characteristics

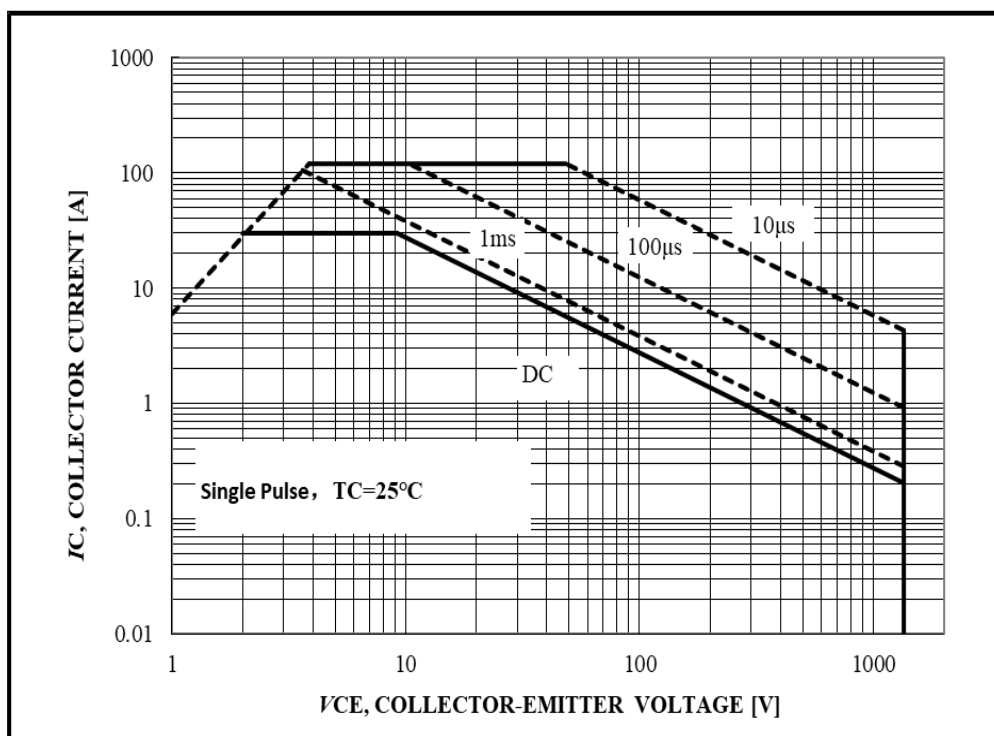


Figure 16. Forward Bias Safe Operating Area

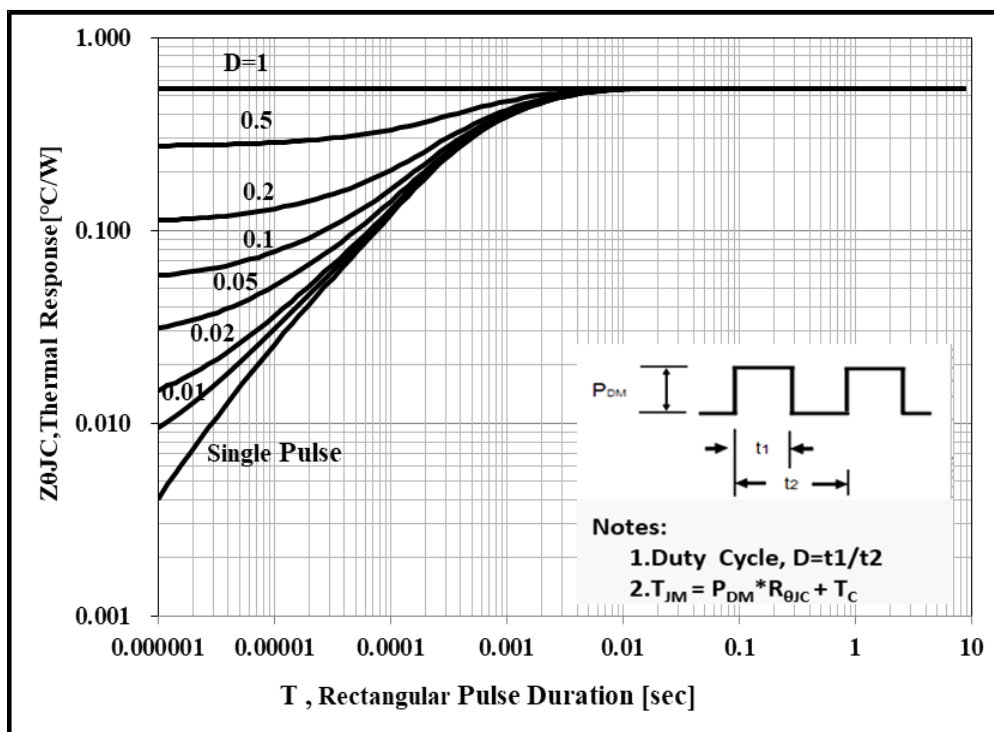
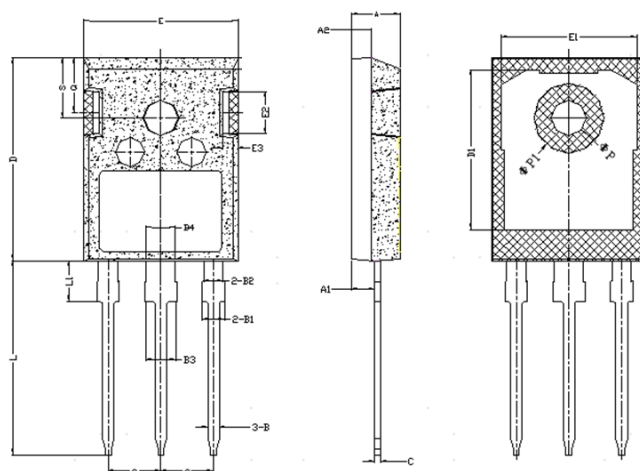


Figure 17. IGBT Transient Thermal Impedance

Package Information



Items	Values(mm)	
	MIN	MAX
A	4.6	5.2
A1	2.2	2.6
A2	1.85	2.17
B	0.9	1.4
B1	1.75	2.35
B2	1.75	2.15
B3	2.8	3.35
B4	2.8	3.15
C	0.5	0.7
D	20.60	21.30
D1	16	18
E	15.5	16.10
E1	13	14.7
E2	3.80	5.3
E3	0.8	2.60
e	5.2	5.7
L	19	20.5
L1	3.9	4.6
ΦP	3.3	3.70
ΦP1	7.0	7.4
Q	5.2	6.00
S	5.8	6.6

TO-247 Package

The name and content of poisonous and harmful material in products

Part's Name Limit	Hazardous Substance									
	Pb	Hg	Cd	Cr(VI)	PBB	PBDE	DIBP	DEHP	DBP	BBP
	≤0.1%	≤0.1%	≤0.01%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%
Lead Frame	○	○	○	○	○	○	○	○	○	○
Molding	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
Wire Bonding	○	○	○	○	○	○	○	○	○	○
Solder	×	○	○	○	○	○	○	○	○	○
Note	○: Means the hazardous material is under the criterion of 2011/65/EU. ×: Means the hazardous material exceeds the criterion of 2011/65/EU. The plumbum element of solder exist in products presently, but within the allowed range of Eurogroup's RoHS.									

Warnings

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. It is suggested to be used under 80 percent of the maximum ratings of the device.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. IGBTs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. This publication is made by Huajing Microelectronics and subject to regular change without notice.

WUXI CHINA RESOURCES HUAJING MICROELECTRONICS CO., LTD.

Add: No.14 Liangxi RD. Wuxi, Jiangsu, China Mail: 214061 <https://www.crmicro.com>
Tel: 0510-85807228 Fax: 0510-85800864

Marketing Part: Post: 214061 Tel / Fax: 0510-85807228-3663/5508
0510-85800360 (Fax)

Application and Service: Post: 214061 Tel / Fax: 0510-85807228-3399 / 2227

Modify :

Version	Modify record
2025V01	Initial release